

Domain :	bhel.abcprocure.com																						
Parent department:	CFP RUDRAPUR																						
Event ID	: 47122	RFQ/NIT/Enquiry no. : 202002461																					
Description	: FRAMEWORK AGREEMENT FOR SILVER PLATING ON ALUMINIUM AND COPPER CONDUCTOR/PALM/BLANKING PLATES INCLUDING HANDLING, POLISHING BUFFING ON ITEMS F.O.R BHEL RUDRAPUR BASIS.																						
Corrigendum / Amendment No :1 (Published) (09/10/2020 15:24:25)																							
Types of corrigendum :	1) Others																						
Corrigendum Text :	<div>1. Regarding Silver Plating thickness: The material code calls for General Instruction as per drawing No.45410001025 Rev 11 which states that, “SILVER PLATING SHALL BE MINIMUM 13 MICRON”. for both line items. 2. Additional Page of Annexure - B (Tech-Coml. Terms & Conditions) attached.</div>																						
Documents																							
<table><thead><tr><th>Document name</th><th>Document brief</th><th>Size (in MB)</th><th>Date and time</th><th>Status</th><th>Action</th></tr></thead><tbody><tr><td>Surface Preparation 45410001025R11.pdf</td><td>45410001025</td><td>0.305</td><td>09/10/2020 14:25:31</td><td>Approved</td><td>Download link</td></tr><tr><td>ANNEXURE B TECH COML CONDITIONS.PDF</td><td>ANNEXURE B TECH COML CONDITIPMS</td><td>0.326</td><td>08/10/2020 09:06:07</td><td>Approved</td><td>Download link</td></tr></tbody></table>						Document name	Document brief	Size (in MB)	Date and time	Status	Action	Surface Preparation 45410001025R11.pdf	45410001025	0.305	09/10/2020 14:25:31	Approved	Download link	ANNEXURE B TECH COML CONDITIONS.PDF	ANNEXURE B TECH COML CONDITIPMS	0.326	08/10/2020 09:06:07	Approved	Download link
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